

Low-Voltage Quad 2-Input Exclusive-OR Gate with 5 V Tolerant Inputs

74LCX86

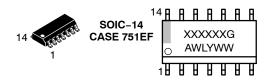
The 74LCX86 is a high performance, quad 2-input XOR gate The LCX86 contains four 2-input exclusive-OR gates. The inputs tolerate voltages up to 5.5 V allowing the interface of 5 V systems to 3 V systems.

The 74LCX86 is fabricated with advanced CMOS technology to achieve high speed operation while maintaining CMOS low power dissipation.

Features

- 5 V Tolerant Inputs
- 1.65 V–5.5 V V_{CC} Specifications Provided
- 6.5 ns t_{PD} Max. ($V_{CC} = 3.3 \text{ V}$), 10 μ A I_{CC} Max.
- Power-down High Impedance Inputs and Outputs
- ± 24 mA Output Drive ($V_{CC} = 3.0 \text{ V}$)
- Implements Proprietary Noise/EMI Reduction Circuitry
- Latch-up Performance Exceeds 100 mA
- ESD Performance
 - ♦ Machine Model > 2000 V
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

MARKING DIAGRAMS







XXXXXX = Specific Device Code
A = Assembly Location

L, WL = Wafer Lot Y, YY = Year W, WW = Work Week G or = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information on page 7 of this data sheet.

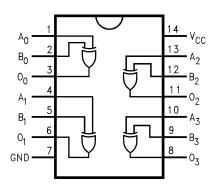


Figure 1. Connection Diagram

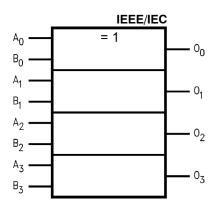


Figure 2. Logic Symbol

PIN DESCRIPTION

| Pin Names | Description |
|--------------------------------|-------------|
| A ₀ -A ₃ | Inputs |
| B ₀ -B ₃ | Inputs |
| O ₀ -O ₃ | Outputs |

MAXIMUM RATINGS

| Symbol | Parameter | | Value | Unit |
|--|--|--|---|------|
| V _{CC} | DC Supply Voltage | | -0.5 to +6.5 | V |
| V _I | DC Input Voltage (Note 1) | | -0.5 to +6.5 | V |
| Vo | | ode (High or Low State) Tri-State Mode Down Mode (V _{CC} = 0 V) | -0.5 to V _{CC} + 0.5 -0.5 to +6.5 -0.5 to +6.5 | V |
| I _{IK} | DC Input Diode Current | V _I < GND | -50 | mA |
| I _{OK} | DC Output Diode Current | V _O < GND | -50 | mA |
| I _O | DC Output Source/Sink Current | | ±50 | mA |
| I _{CC} or I _{GND} | DC Supply Current per Supply Pin or Ground Pin | | ±100 | mA |
| T _{STG} | Storage Temperature Range | | -65 to +150 | °C |
| T _L | Lead Temperature, 1 mm from Case for 10 secs | | 260 | °C |
| TJ | Junction Temperature Under Bias | | +150 | °C |
| $\theta_{\sf JA}$ | Thermal Resistance (Note 1) | SOIC-14 QFN14 TSSOP-14 | 116 130 150 | °C/W |
| P _D | Power Dissipation in Still Air at 125°C | SOIC-14 QFN14 TSSOP-14 | 1077 962 833 | mW |
| MSL | Moisture Sensitivity | | Level 1 | - |
| F _R | Flammability Rating | Oxygen Index: 28 to 34 | UL 94 V-0 @ 0.125 in | - |
| V _{ESD} | ESD Withstand Voltage (Note 3) | Human Body Model Charged Device Model | 2000 N/A | V |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- 1. I_O absolute maximum rating must be observed.
- Measured with minimum pad spacing on an FR4 board, using 76 mm-by-114 mm, 2-ounce copper trace no air flow per JESD51-7.
 HBM tested to EIA / JESD22-A114-A. CDM tested to JESD22-C101-A. JEDEC recommends that ESD qualification to EIA/JESD22-A115A (Machine Model) be discontinued.

RECOMMENDED OPERATING CONDITIONS

| Symbol | Р | arameter | Min | Тур | Max | Unit |
|---------------------------------|--------------------------------|---|------|-----|----------|------|
| V_{CC} | Supply Voltage | Operating | 1.65 | 3.3 | 5.5 | V |
| | | Data Retention Only | 1.5 | 3.3 | 5.5 | |
| VI | Digital Input Voltage | | 0 | _ | 5.5 | ٧ |
| Vo | Output Voltage | Active Mode (High or Low State) | 0 | - | V_{CC} | V |
| | | Tri-State Mode | 0 | _ | 5.5 | |
| | | Power Down Mode (V _{CC} = 0 V) | 0 | _ | 5.5 | |
| T _A | Operating Free-Air Temperature | | -40 | _ | +125 | °C |
| t _r , t _f | Input Rise or Fall Rate | V _{CC} = 1.65 V to 1.95 V | 0 | - | 20 | nS/V |
| | | $V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$ | 0 | _ | 20 | |
| | | V_I from 0.8 V to 2.0 V, V_{CC} = 3.0 V | 0 | _ | 10 | |
| | | V_{CC} = 4.5 V to 5.5 V | 0 | _ | 5 | |

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

4. Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or V_{CC}). Unused outputs must be left open.

DC ELECTRICAL CHARACTERISTICS

| | | | | T _A = -40 °C | C to +85 °C | T _A = -40 °C | to +125 °C | 1 | |
|------------------|---|--|---|--|---|--|---|------|--|
| Symbol | Parameter | Conditions | V _{CC} (V) | Min | Max | Min | Max | Unit | |
| V _{IH} | HIGH Level Input Voltage | | 1.65 – 1.95 | 0.65 x V _{CC} | - | 0.65 x V _{CC} | _ | V | |
| | | | 2.3 – 2.7 | 1.7 | - | 1.7 | _ | | |
| | | | 3.0 – 3.6 | 2.0 | - | 2.0 | - | | |
| | | | 4.5 – 5.5 | 0.70 x V _{CC} | - | 0.70 x V _{CC} | - | | |
| V _{IL} | LOW Level Input Voltage | | 1.65 – 1.95 | - | 0.35 x V _{CC} | - | 0.35 x V _{CC} | V | |
| | | | 2.3 – 2.7 | - | 0.7 | - | 0.7 | | |
| | | | 3.0 – 3.6 | - | 0.8 | - | 0.8 | | |
| | | | 4.5 – 5.5 | - | 0.30 x V _{CC} | - | 0.30 x V _{CC} | | |
| V _{OH} | High-Level Output Voltage Low-Level Output Voltage | $\begin{split} V_I &= V_{IH} \text{ or } V_{IL} \\ I_{OH} &= -100 \mu\text{A} \\ I_{OH} &= -4 \text{ mA} \\ I_{OH} &= -8 \text{ mA} \\ I_{OH} &= -12 \text{ mA} \\ I_{OH} &= -16 \text{ mA} \\ I_{OH} &= -24 \text{ mA} \\ I_{OH} &= -32 \text{ mA} \\ \end{split}$ $V_I &= V_{IH} \text{ or } V_{IL} \\ I_{OL} &= 100 \mu\text{A} \\ I_{OL} &= 4 \text{ mA} \\ I_{OL} &= 8 \text{ mA} \\ I_{OL} &= 12 \text{ mA} \end{split}$ | 1.65 to 5.5 1.65 2.3 2.7 3.0 3.0 4.5 1.65 to 5.5 1.65 2.3 2.7 | V _{CC} - 0.1 1.29 1.8 2.2 2.4 2.2 3.7 | - - - - - - 0.1 0.24 0.3 0.4 | V _{CC} - 0.1 1.29 1.8 2.2 2.4 2.2 3.7 | - - - - - - 0.1 0.24 0.3 0.4 | V | |
| l _l | Input Leakage Current | $I_{OL} = 16 \text{ mA}$ $I_{OL} = 24 \text{ mA}$ $I_{OL} = 32 \text{ mA}$ $V_{I} = 0 \text{ to } 5.5 \text{ V}$ | 3.0 3.0 4.5 3.6 | - - - | 0.4 0.55 0.6 ±5.0 | - - - | 0.4 0.55 0.6 ±5.0 | μΑ | |
| l _{OFF} | Power Off Leakage | V _I = 5.5 V or | 0 | _ | 10 | _ | 10 | μΑ | |
| ·UFF | Current | $V_0 = 5.5 \text{ V}$ | | | | | | μιν | |
| I _{CC} | Quiescent Supply Current | V _I = 5.5 V or GND | 3.6 | - | 10 | - | 10 | μΑ | |
| ΔI_{CC} | Increase in I _{CC} per Input | V _{IH} = V _{CC} - 0.6 V | 2.3 to 3.6 | - | 500 | - | 500 | μΑ | |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

AC ELECTRICAL CHARACTERISTICS

| | | | | T _A = -40 °C | C to +85 °C | T _A = -40 °C | to +125 °C | | | | | | | |
|-------------------------------------|--------------------|---------------------|---------------------|-------------------------|-------------|-------------------------|------------|------|--|------------|---|-----|---|-----|
| Symbol | Parameter | Test Condition | V _{CC} (V) | Min | Max | Min | Max | Unit | | | | | | |
| t _{PLH} , t _{PHL} | Propagation Delay, | See Figures 3 and 4 | 1.65 to 1.95 | - | 12.0 | - | 12.0 | ns | | | | | | |
| | Input to Output | | anu 4 | 2.3 to 2.7 | - | 7.8 | - | 7.8 | | | | | | |
| | | | 2.7 | - | 7.0 | - | 7.0 | | | | | | | |
| | | | | | | | | | | 3.0 to 3.6 | - | 6.5 | - | 6.5 |
| | | | 4.5 to 5.5 | - | 4.5 | - | 4.5 | | | | | | | |

AC ELECTRICAL CHARACTERISTICS

| | | | | T _A = -40 °C | C to +85 °C | T _A = -40 °C | to +125 °C | |
|---------------------|-----------------------|----------------|---------------------|-------------------------|-------------|-------------------------|------------|------|
| Symbol | Parameter | Test Condition | V _{CC} (V) | Min | Max | Min | Max | Unit |
| t _{OSHL} , | Output to Output Skew | | 1.65 to 1.95 | - | - | _ | - | ns |
| toslh | | | 2.3 to 2.7 | - | - | _ | - | |
| | | | 2.7 | - | - | _ | - | |
| | | | 3.0 to 3.6 | - | 1.0 | _ | 1.0 | |
| | | | 4.5 to 5.5 | - | - | - | - | |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

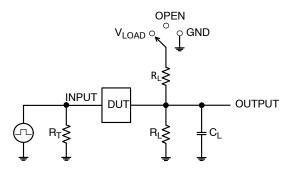
DYNAMIC SWITCHING CHARACTERISTICS

| | | | | T _A = +25 °C | | | |
|------------------|--------------------------|--|---------------------|-------------------------|------|-----|------|
| Symbol | Characteristic | Condition | V _{CC} (V) | Min | Тур | Max | Unit |
| V _{OLP} | Dynamic LOW Peak Volt- | $C_L = 50 \text{ pF}, V_{IH} = 3.3 \text{ V}, V_{IL} = 0 \text{ V}$ | 3.3 | | 0.8 | | V |
| | age (Note 5) | C_L = 30 pF, V_{IH} = 2.5 V, V_{IL} = 0 V | 2.5 | | 0.6 | | |
| V _{OLV} | Dynamic LOW Valley Volt- | $C_L = 50 \text{ pF}, V_{IH} = 3.3 \text{ V}, V_{IL} = 0 \text{ V}$ | 3.3 | | -0.8 | | V |
| | age (Note 5) | C _L = 30 pF, V _{IH} = 2.5 V, V _{IL} = 0 V | 2.5 | | -0.6 | | |

^{5.} Number of outputs defined as "n". Measured with "n-1" outputs switching from HIGH-to-LOW or LOW-to-HIGH. The remaining output is measured in the LOW state.

CAPACITIVE CHARACTERISTICS

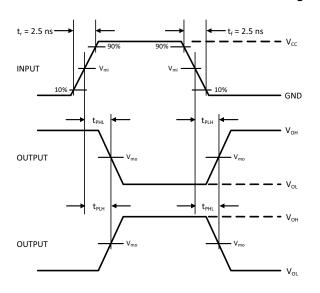
| Symbol | Parameter | Parameter Condition | | Unit |
|------------------|-------------------------------|--|----|------|
| C _{IN} | Input Capacitance | V_{CC} = 3.3 V, V_{I} = 0 V or V_{CC} | 7 | pF |
| C _{OUT} | Output Capacitance | V_{CC} = 3.3 V, V_{I} = 0 V or V_{CC} | 8 | pF |
| C _{PD} | Power Dissipation Capacitance | $f = 10 \text{ MHz}, V_{CC} = 3.3 \text{ V}, V_{I} = 0 \text{ V or } V_{CC}$ | 25 | pF |

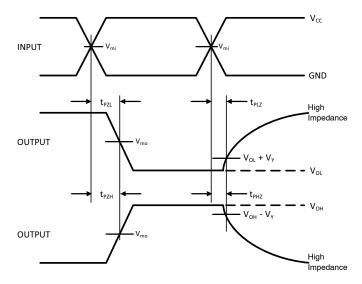


| Test | Switch Position |
|-------------------------------------|-----------------|
| t _{PLH} / t _{PHL} | Open |
| t _{PLZ} / t _{PZL} | V_{LOAD} |
| t _{PHZ} / t _{PZH} | GND |

 C_L includes probe and jig capacitance R_T is Z_{OUT} of pulse generator (typically 50 $\Omega)$ f = 1 MHz

Figure 3. Test Circuit





| V _{CC} , V | R_L,Ω | C _L , pF | V _{LOAD} | V _m , V | V _Y , V |
|---------------------|--------------|---------------------|---------------------|--------------------|--------------------|
| 1.65 to 1.95 | 500 | 30 | 2 x V _{CC} | V _{CC} /2 | 0.15 |
| 2.3 to 2.7 | 500 | 30 | 2 x V _{CC} | V _{CC} /2 | 0.15 |
| 2.7 | 500 | 50 | 6 V | 1.5 | 0.3 |
| 3.0 to 3.6 | 500 | 50 | 6 V | 1.5 | 0.3 |
| 4.5 to 5.5 | 500 | 50 | 2 x V _{CC} | V _{CC} /2 | 0.3 |

Figure 4. Switching Waveforms

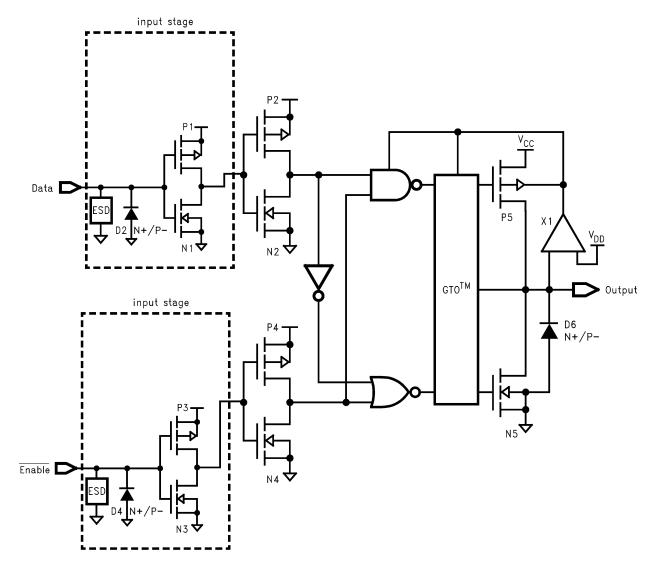


Figure 5. Schematic Diagram (Generic for LCX Family)

ORDERING INFORMATION

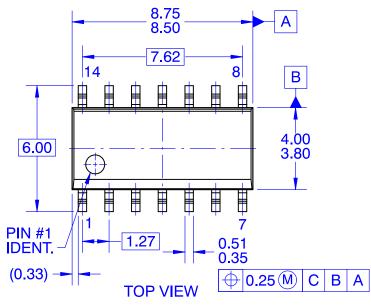
| Device | Marking | Package | Shipping [†] |
|-------------|-----------|----------|-----------------------|
| 74LCX86MTCX | LCX 86 | TSSOP-14 | 2500 / Tape & Reel |

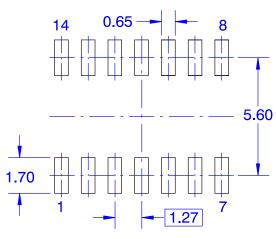
[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.



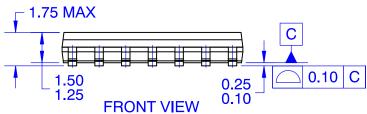
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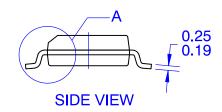
DATE 30 SEP 2016





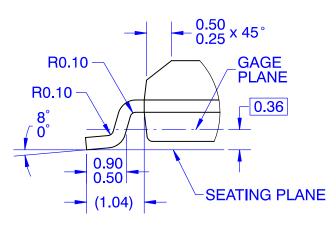
LAND PATTERN RECOMMENDATION





NOTES:

- A. CONFORMS TO JEDEC MS-012, VARIATION AB, ISSUE C
 B. ALL DIMENSIONS ARE IN MILLIMETERS
- C. DIMENSIONS DO NOT INCLUDE MOLD FLASH OR BURRS
- D. LAND PATTERN STANDARD:
- SOIC127P600X145-14M
- E. CONFORMS TO ASME Y14.5M, 2009

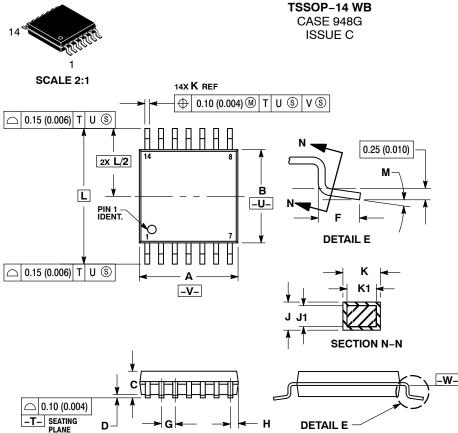


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DATE 17 FEB 2016

- NOTES.

 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

 2. CONTROLLING DIMENSION: MILLIMETER.

 3. DIMENSION A DOES NOT INCLUDE MOLD
- FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
 DIMENSION B DOES NOT INCLUDE
- INTERLEAD FLASH OR PROTRUSION.
 INTERLEAD FLASH OR PROTRUSION SHALL
- INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.

 DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.

 TERMINAL NUMBERS ARE SHOWN FOR DEEEDENIC OMITY.
- REFERENCE ONLY.
 DIMENSION A AND B ARE TO BE
- DETERMINED AT DATUM PLANE -W-.

| | MILLIMETERS | | INCHES | |
|-----|-------------|------|-----------|-------|
| DIM | MIN | MAX | MIN | MAX |
| Α | 4.90 | 5.10 | 0.193 | 0.200 |
| В | 4.30 | 4.50 | 0.169 | 0.177 |
| С | | 1.20 | | 0.047 |
| D | 0.05 | 0.15 | 0.002 | 0.006 |
| F | 0.50 | 0.75 | 0.020 | 0.030 |
| G | 0.65 BSC | | 0.026 BSC | |
| Н | 0.50 | 0.60 | 0.020 | 0.024 |
| J | 0.09 | 0.20 | 0.004 | 0.008 |
| J1 | 0.09 | 0.16 | 0.004 | 0.006 |
| K | 0.19 | 0.30 | 0.007 | 0.012 |
| K1 | 0.19 | 0.25 | 0.007 | 0.010 |
| L | 6.40 BSC | | 0.252 BSC | |
| м | o ° | 8 ° | o ° | a ° |

GENERIC MARKING DIAGRAM*



= Assembly Location

L = Wafer Lot = Year

= Work Week W

= Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

RECOMMENDED SOLDERING FOOTPRINT*

| - | 7.06 |
|-----------------|-------------------------|
| 1 | |
| | |
| | |
| | |
| | 0.65 PITCH |
| ↓ □ | |
| 14X 0.36 126 | |
| 0.36 - 1.26 | DIMENSIONS: MILLIMETERS |

*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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|------------------|-------------|---|-------------|--|
| DESCRIPTION: | TSSOP-14 WB | | PAGE 1 OF 1 | |

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